

SN5454, SN54LS54, SN7454, SN74LS54 4-WIDE AND-OR-INVERT GATES

SDLS115

DECEMBER 1983—REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

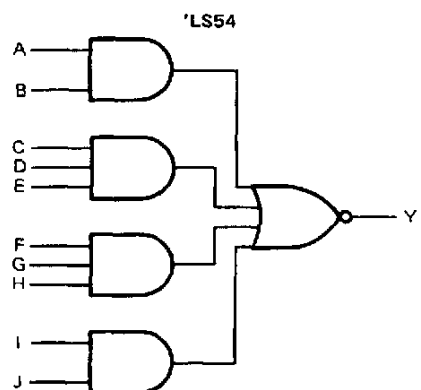
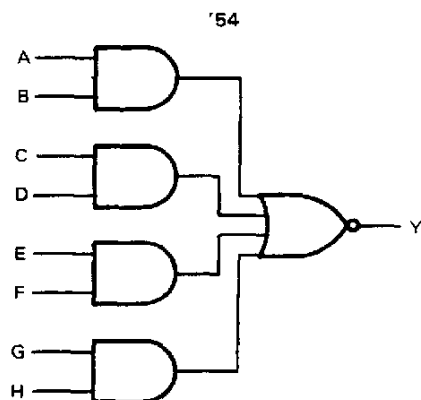
description

These devices contain 4-wide AND-OR-INVERT gates. They perform the following Boolean functions:

$$\begin{aligned} \text{'54 } Y &= \overline{AB + CD + EF + GH} \\ \text{LS54 } Y &= \overline{AB + CDE + FGH + IJ} \end{aligned}$$

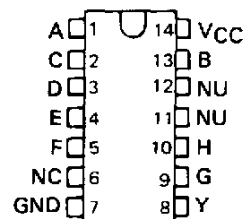
The SN5454 and SN54LS54 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7454 and SN74LS54 are characterized for operation from 0°C to 70°C .

logic diagrams (positive logic)



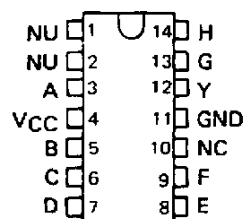
SN5454 . . . J PACKAGE
SN7454 . . . N PACKAGE

(TOP VIEW)



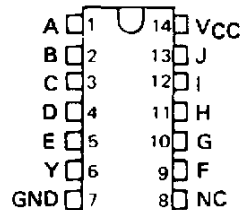
SN5454 . . . W PACKAGE

(TOP VIEW)



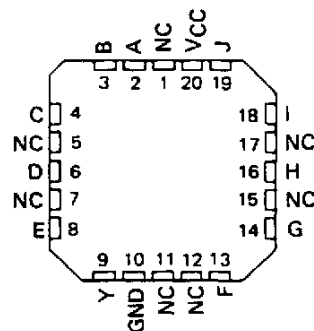
SN54LS54 . . . J OR W PACKAGE
SN74LS54 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS54 . . . FK PACKAGE

(TOP VIEW)



NC—No internal connection
NU—Make no external connection

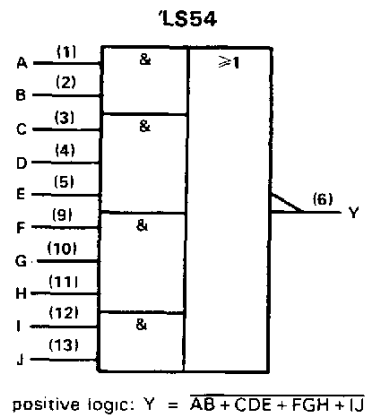
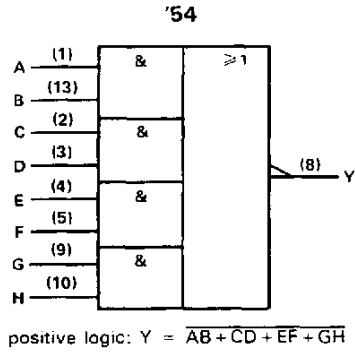
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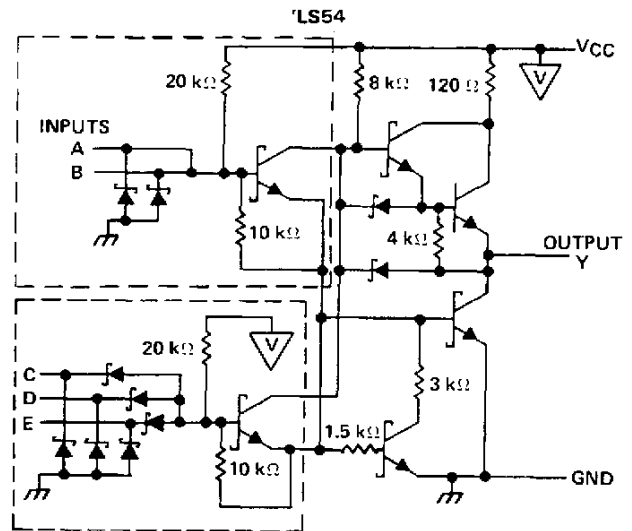
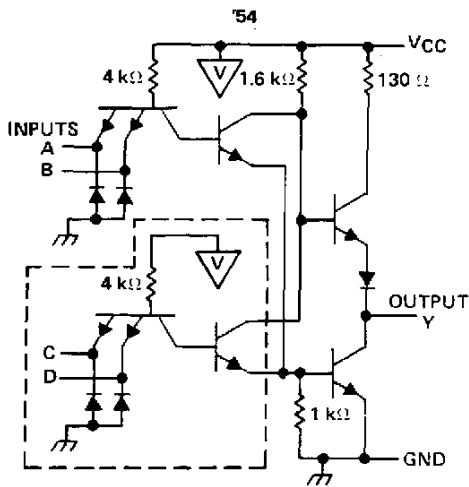
SN5454, SN54LS54, SN7454, SN74LS54 4-WIDE AND-OR-INVERT GATES

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N package. For the SN54LS54 only, they apply also for the W package.

schematics



Resistor values shown are nominal.

The portion of the circuits within the dashed lines is repeated for each additional 2- or 3-input AND section, as shown in the logic diagram and logic symbols.

SN5454, SN7454 4-WIDE AND-OR-INVERT GATES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature: SN5454	-55°C to 125°C
SN7454	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN5454			SN7454			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
I_{OH} High-level output current			-0.4			-0.4	mA
I_{OL} Low-level output current			16			16	mA
T_A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN5454			SN7454			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V_{IK}	$V_{CC} = \text{MIN.}$, $I_I = -12 \text{ mA}$			-1.5			-1.5	V
V_{OH}	$V_{CC} = \text{MIN.}$, $V_{IL} = 0.8 \text{ V}$, $I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		V
V_{OL}	$V_{CC} = \text{MIN.}$, $V_{IH} = 2 \text{ V}$, $I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
I_I	$V_{CC} = \text{MAX.}$, $V_I = 5.5 \text{ V}$			1			1	mA
I_{IH}	$V_{CC} = \text{MAX.}$, $V_I = 2.4 \text{ V}$			40			40	μA
I_{IL}	$V_{CC} = \text{MAX.}$, $V_I = 0.4 \text{ V}$			-1.6			-1.6	mA
$I_{OS}§$	$V_{CC} = \text{MAX.}$	-20		-55	-18		-55	mA
I_{CCH}	$V_{CC} = \text{MAX.}$, $V_I = 0 \text{ V}$		4	8		4	8	mA
I_{CCL}	$V_{CC} = \text{MAX.}$, See Note 2		5.1	9.5		5.1	9.5	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

[§] Not more than one output should be shorted at a time.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	$R_L = 400 \Omega$, $C_L = 15 \text{ pF}$		13	22	ns
t_{PHL}					8	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN54LS54, SN74LS54 4-WIDE AND-OR-INVERT GATES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature: SN54LS54	-55°C to 125°C
SN74LS54	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS54			SN74LS54			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
I_{OH} High-level output current			-0.4			-0.4	mA
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS54		SN74LS54		UNIT		
		MIN	TYP ‡	MAX	MIN		TYP ‡	MAX
V_{IK}	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5		-1.5	V	
V_{OH}	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, I_{OH} = -0.4 \text{ mA}$	2.5	3.4		2.7	3.4	V	
V_{OL}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, I_{OL} = 8 \text{ mA}$					0.35	0.5	V
I_I	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.1		0.1	mA	
I_{IH}	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			20		20	μA	
I_{IL}	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-0.4		-0.4	mA	
$I_{OS}§$	$V_{CC} = \text{MAX}$	-20		-100	-20	-100	mA	
I_{CCH}	$V_{CC} = \text{MAX}, V_I = 0 \text{ V}$		0.8	1.6		0.8	1.6	mA
I_{CCL}	$V_{CC} = \text{MAX}, \text{ See Note 2}$		1	2		1	2	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF}$		12	20	ns
t_{PHL}					12.5	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN5454J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7454N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7454N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5454J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5454J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5454W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5454W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS54FK	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS54FK	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

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PACKAGING INFORMATION

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SN7454N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5454J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5454J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5454W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5454W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS54FK	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS54FK	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

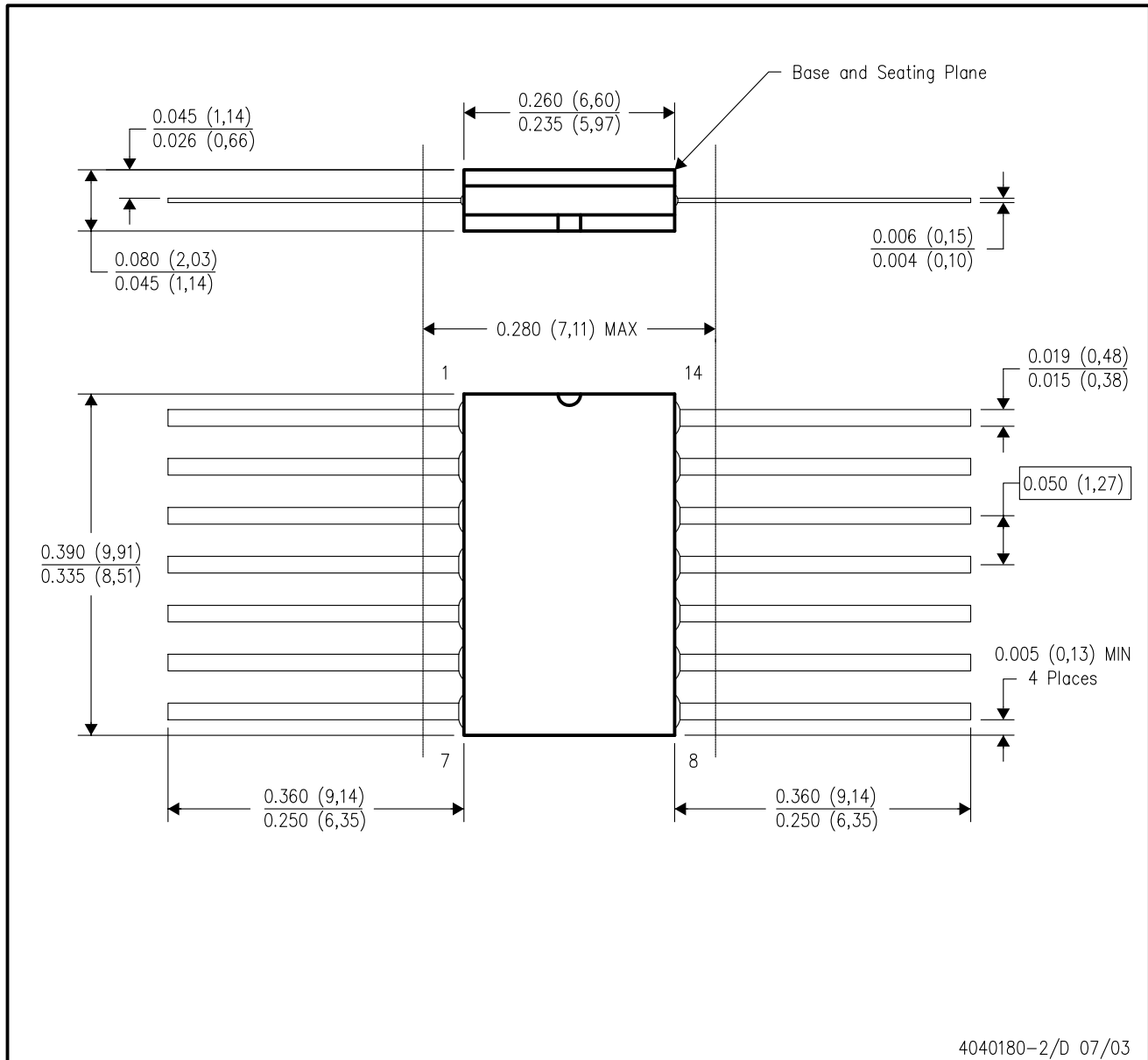


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

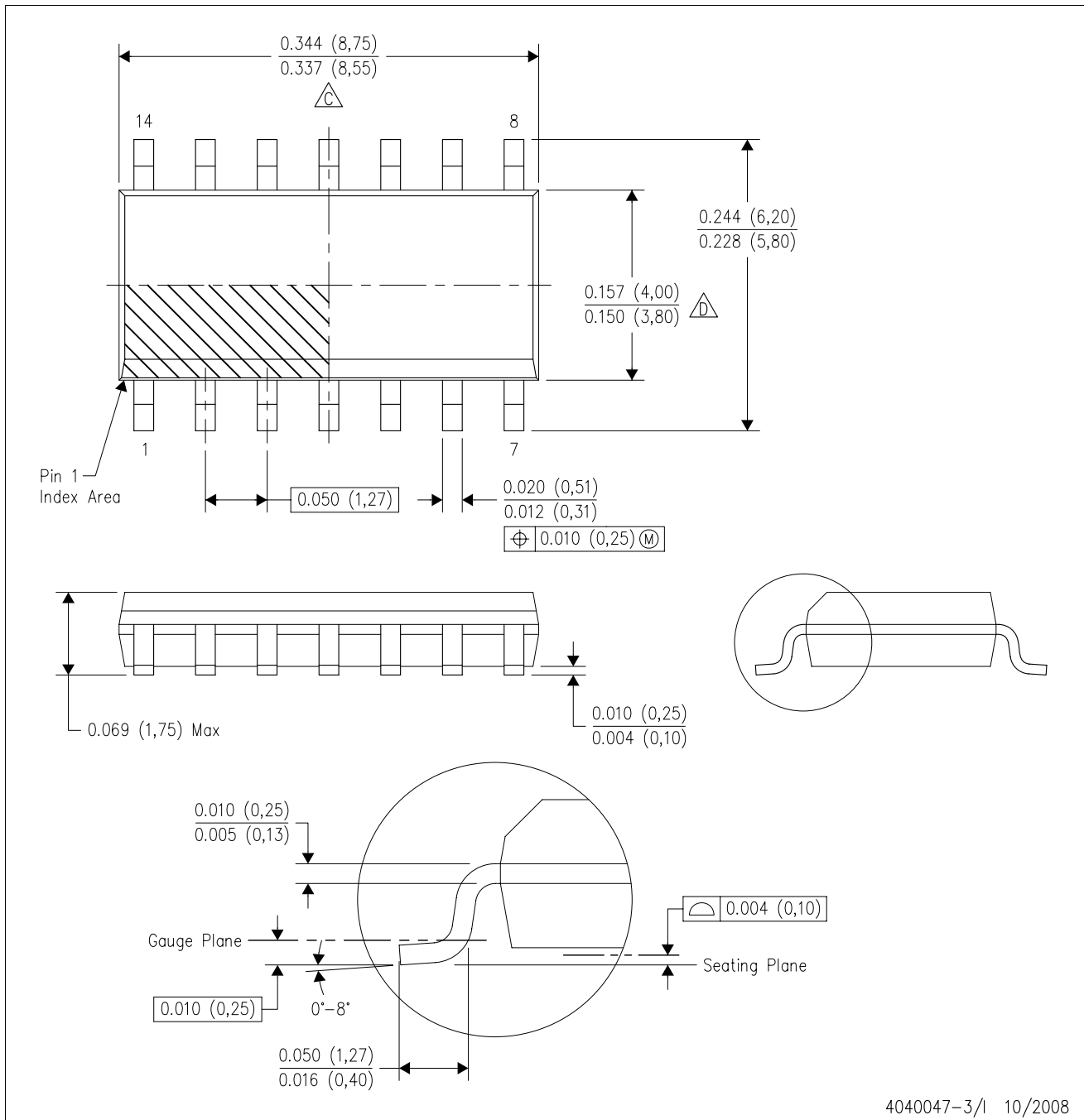
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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